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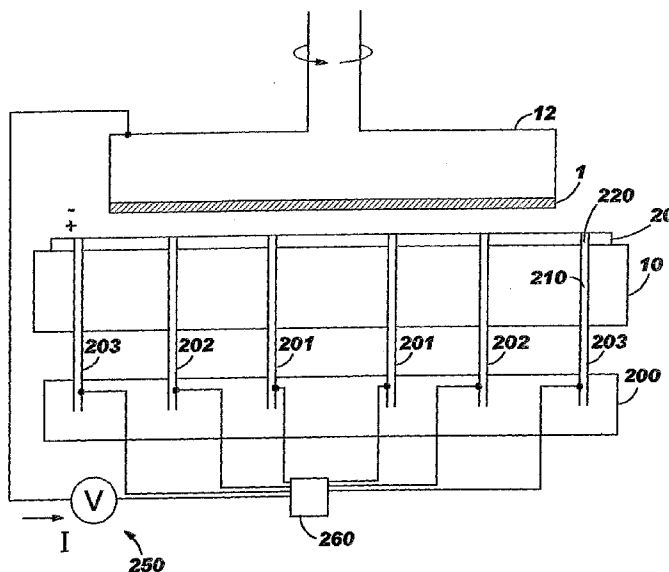
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(54) Title: INTEGRATED PLATING AND PLANARIZATION PROCESS AND APPARATUS THEREFOR



(57) Abstract: A method and apparatus are described for performing both electroplating of a metal layer and CMP planarization of the layer on a substrate. The apparatus includes a table (10) supporting a polishing pad (20); the table and pad have a plurality of holes (210, 220) forming channels for dispensing an electroplating solution onto the pad. Electroplating anodes (201, 202, 203) are disposed in the channels and in contact with the electroplating solution. A carrier (12) holds the substrate (1) substantially parallel to the top surface of the pad (20) and applies variable mechanical force on the substrate against the pad, so that the spacing between substrate and pad may be less during electroplating than during electroetching.

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